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FROM-CROMPTON SEAGER TUFFE LLC

T-195 P.06/08 F-726

| FORM PTO-1449 | Atty. Docket No.: 1100.1138101 (H16-17400) | Serial No 10/007,288 |
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| | Applicant: Wood et al | • |
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| DISCLOSURE STATEMENT | December 3, 2001 | 1745 |

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EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.